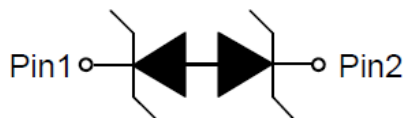


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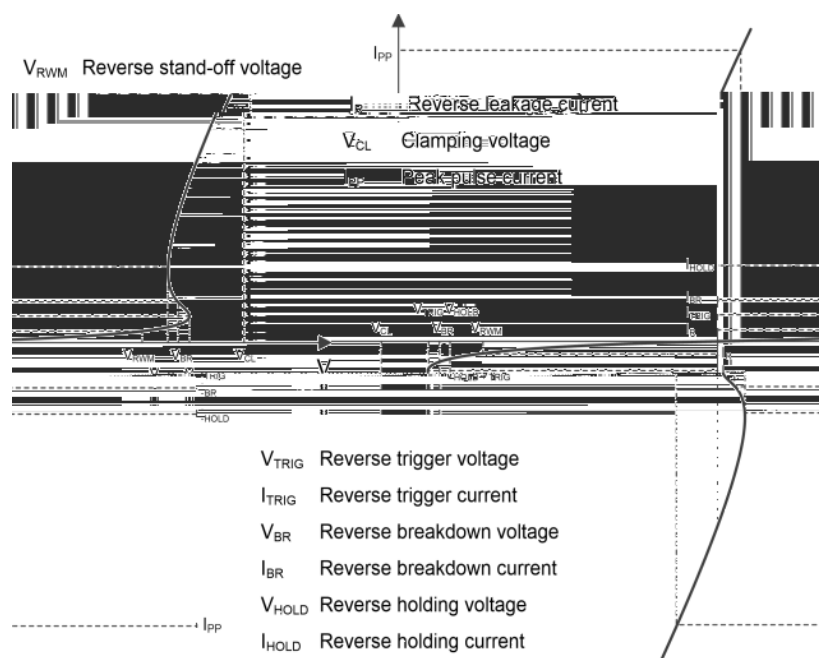
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□



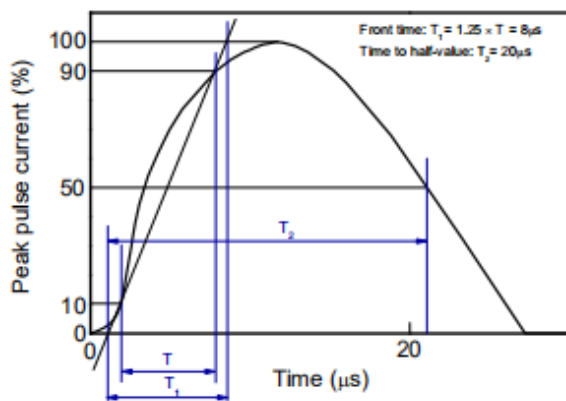
μ			
μ			
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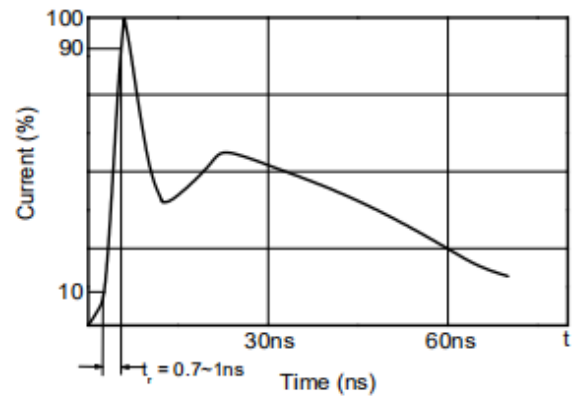
					±	
						Ω
			μ			
			μ			

Notes:

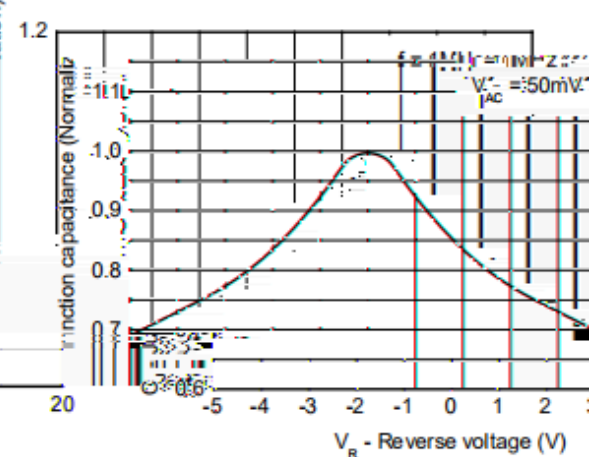
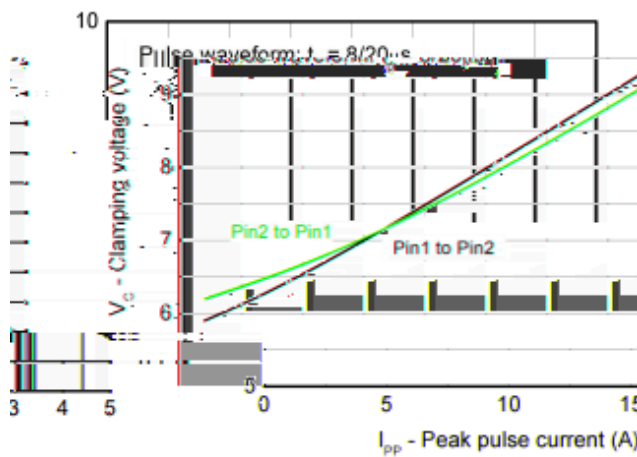
- 1) TLP parameter: $Z_0 = 50\Omega$, $t_p = 100ns$, $t_r = 2ns$, averaging window from 60ns to 80ns. RDYN is calculated from 4A to 16A.
- 2) Contact discharge mode, according to IEC61000-4-2.
- 3) Non-repetitive current pulse, according to IEC61000-4-5.



8/20 μs waveform per IEC61000-4-5



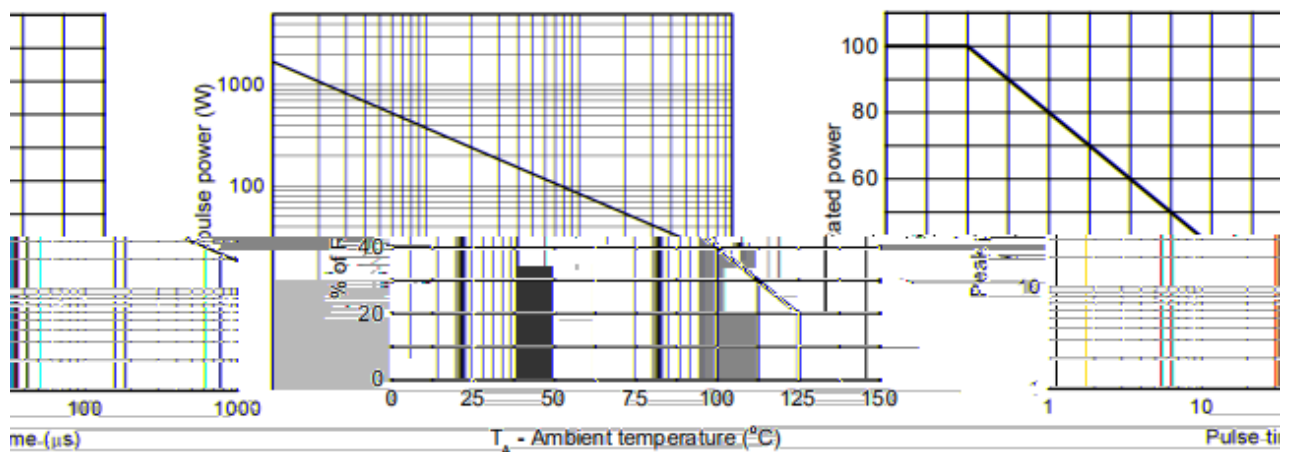
Contact discharge current waveform per IEC61000-4-2



oltage

Clamping voltage vs. Peak pulse current

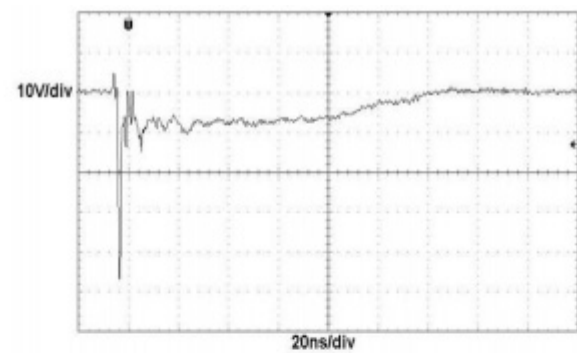
Capacitance vs. Reverse v



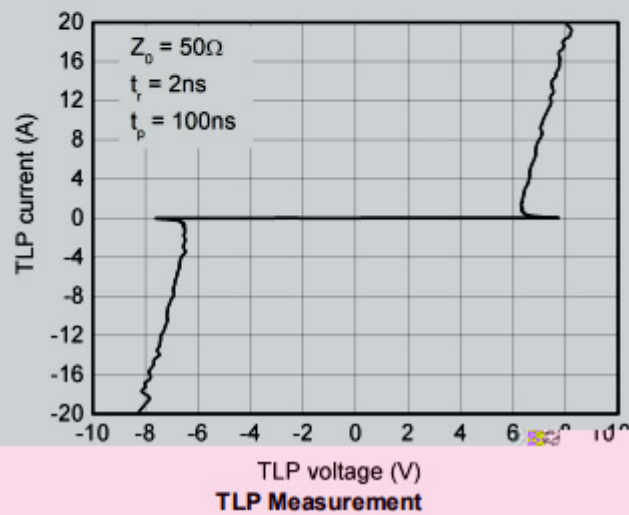
pulse power vs. Pulse time

Power derating vs. Ambient temperature

Non-repetitive peak p

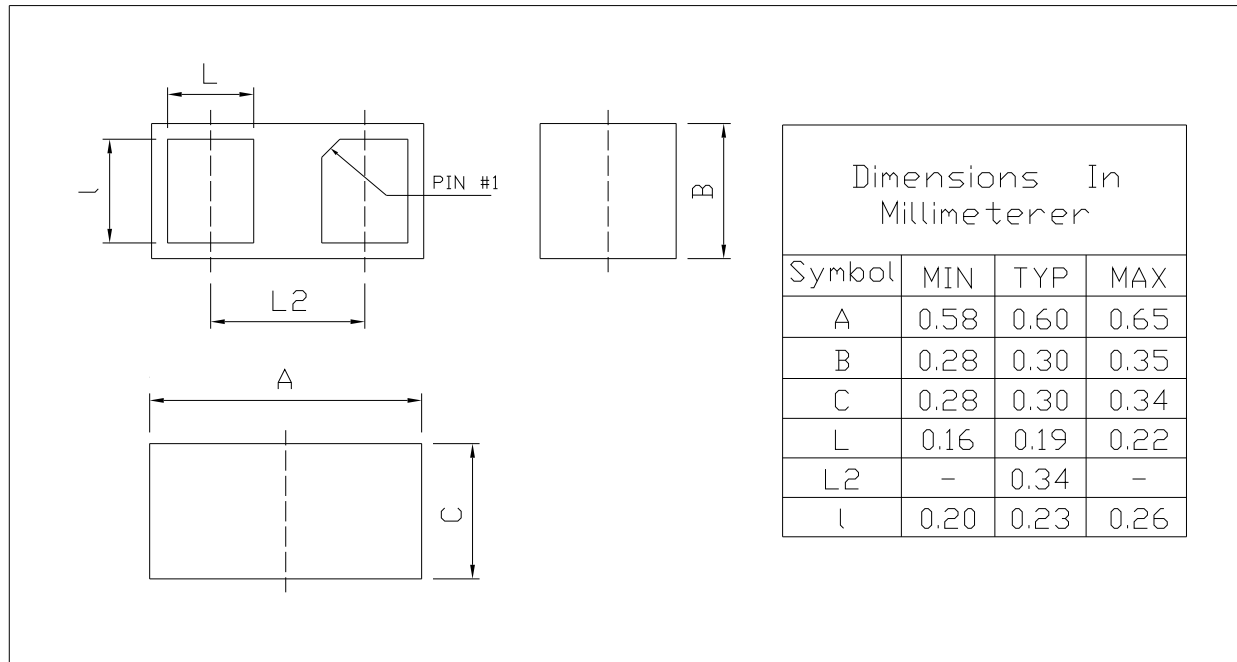


ESD clamping
(-8kV contact discharge per IEC61000-4-2)



DFN0603

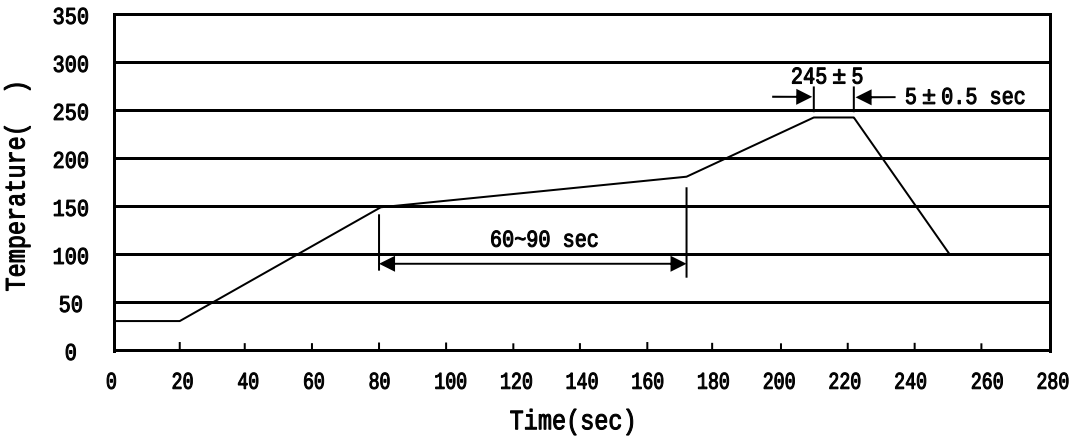
Unit:mm



Rev.02 202102



Temperature Profile for IR Reflow Soldering(Pb-Free)



封装形式	包装数量					包装尺寸		
	只 卷盘	卷盘 盒	只 盒	盒 箱	只 箱		盒	箱